1999 EDITORIAL INDEX

COMMUNICATIONS

•LMDS set to challenge for last-mile supremacy (April, p. 30)
•Growth beckons in millimeter-wave markets (April, p. 122)
•Modulation formats drive communications design (May, p. 80)
•Communications technologies take aim on the millennium (May, p. 160)
•Wireless ushers in the era of personal connectivity (August, p. 31)
•Communications lifts off into inner space (September, p. 31)
•Predict phase-noise effects in digital communications systems (September, p. 59)
•Canada extends borders of RF technology (October, p. 29)
•Crystal/oscillator markets look to wireless growth (November, p. 33)

COMPONENTS

•Methods linearize RF transmitters and power amps (January, p. 79)
•Technology fuels firm's entry into filter market (January Cover, p. 113)
•GaAs amplifiers power applications past 18 GHz (January, p. 126)
•Rugged RF coaxial cable is environmentally friendly (February, p. 99)
•Simplify filter tuning in the time domain (March, p. 68)
•Advance improves DC-to-DC converters (March, p. 143)
•Radio links WLL sites at 3.5 GHz (March, p. 146)
•Solder-free resistors endure thermal cycling (March, p. 154)
•Nodal voltages offer key to filter design (April, p. 72)
•Optically controlled RF switches combat EMI (April, p. 86)
•YIG-based synthesizers shave digital phase noise (April, p. 142)
•Bandpass filters require no tuning (April, p. 152)
•Fixed-frequency and smart synthesizers tune to 2.8 GHz (April, p. 155)
•Flexible cables connect precision test equipment (April, p. 156)
•Flat-panel antenna aids mobile satcom (April, p. 158)
•Smart-antenna technology is the wave of the wireless future (May, p. 29)
•Antenna-test ground plane sets the size record (May, p. 39)
•Aligning filters with nodal voltages (May, p. 67)
•Designing antennas for cellular telephones (May, p. 70)
•Phase-locked loops cut current requirements (May, p. 206)
•PTFE dielectric raises trimmer reliability (May, p. 208)
•SMT passive components save circuit-board space (May, p. 218)
•Reviewing fractional-N frequency synthesis (June, p. 53)
•Use single diode to design antenna Tx/Rx switch (June, p. 99)
•New firm manufactures solid connections (June, p. 142)
•PA technology sets base-station priorities (July, p. 27)
•Evaluate the performance of RF power amplifiers (July, p. 61)
•Develop trimless voltage-controlled oscillators (July, p. 68)
•Splitters/combiners team with RF LDMOS in UMTS amp (July, p. 80)
•Linear power hybrid amplifies PCS applications (July Cover, p. 105)
•Combiner/duplexer reduces cost in AMPS/PCS co-location (July, p. 111)
•Quadrature hybrid couplers serve narrowband applications (August, p. 44)
•Design interdigital bandpass filters using LTCC circuits (August, p. 77)
•Novel coaxial connector aids in-vehicle phone users (August, p. 88)
•Splitters/combiners bond high-power amplifiers (August, p. 151)
•Schottky mixers feature high dynamic range (August, p. 154)
•Doublers drive YIG sources to 44 GHz (August, p. 164)
•Develop a high-Q oscillator for millimeter-wave applications (September, p. 72)
•Study antenna positioning and EM biological effects

(September, p. 76)
•Design loop filters for PLL frequency synthesizers (September, p. 98)
•Examine the impact of transition-band spurs on downconverters (September, p. 107)
•Design approach yields broadband directional couplers (September, p. 113)
•Power modules reduce amplifier design time (September, p. 153)
•Firm fosters co-military filter-design approach (September, p. 154)
•Coaxial contacts offer low loss and high repeatability past 6 GHz (September, p. 158)
•Design a wideband VHF filter with coupled resonators (October, p. 59)
•Spurious couplings degrade bandpass filter performance (October, p. 109)
•Wideband choke biases amplifier circuits to 8 GHz (October Cover, p. 131)
•Improvements yield cables with lower loss and enhanced stability (October, p. 148)
•PLL synthesizers suit low-power wireless systems (October, p. 150)
•Exploit leakage inductance in VCO designs (November, p. 59)
•Offset PLL analysis can cut spurious levels (November, p. 107)
•Spurious couplings degrade bandpass filter performance (November, p. 121)
•Techniques yield tiny hairpin-line resonator filters (November, p. 142)
•Electronically shaped antennas link LMDS (November, p. 177)
•Linear amps drive multichannel systems (November, p. 179)
•Looking back at the electronics century (December, p. 31)
•One company's quest for balance (December, p. 38)
•Design a low-noise communications amplifier (December, p. 59)
•Construct a millimeter-wave E-plane integrated power combiner (December, p. 67)
•Manufacturing practical 28-GHz multichip modules (December, p. 78)
•Top Products OF 1999 (December, p. 223)
•Compact coaxial switch fits single-slot VXI card (December, p. 236)
•Baseband processor supports many wireless standards (December, p. 246)

COMPUTER-AIDED ENGINEERING

•Software analyzes curved surfaces (January, p. 122)
•Models describe microstrip circuit characteristics (February, p. 64)
•Accurately compute PLL charge-pump filter parameters (February, p. 89)
•Applying Volterra-Series analysis (May, p. 55)
•Webwatch section (May, p. 174)
•Popular wireless course comes to CD-ROM (June, p. 107)
•System software receives improvements (June, p. 108)
•Program processes engineering data files (June, p. 113)
•Software tracks substrate crosstalk (June, p. 114)
•SPICE software features schematic probing (June, p. 117)
•Software yields filters for 28-to-31-GHz band (June, p. 121)
•Test software and tuners support CAE program (June, p. 137)
•Math package makes most of windows (July, p. 114)
•Synthesis + simulation = enhanced design process (August, p. 123)
•Low-cost CAE suite adds power and speed (August Cover, p. 141)
•EM simulator is free of charge (August, p. 152)
•Software simplifies IR communications (August, p. 160)
•Free EM software analyzes spiral inductor on silicon (September, p. 165)
•Simple algorithm extracts SiGe HBT parameters (October, p. 48)
•Software simplifies large-signal transistor modeling (October, p. 75)
•Model PLL dynamics and phase-noise performance (November, p. 69)
•Nonlinear simulator speeds source design (November, p. 115)
•Webwatch section (November, p. 151)
•Company's rebirth includes major EDA software release (November Cover, p. 165)
•Linear simulator tracks circuit performance (November, p. 181)
•EM software helps refine EIA klystron design (December, p. 74)
•Software models 10-Gb/s differential amplifier (December, p. 184)
•Software simplifies linear circuit analysis (December, p. 196)
•Economical package aids design of linear circuits (December, p. 200)
•Software upholds new design standards (December, p. 202)
•Toolset sorts through signal content (December, p. 204)
•Tool tackles digital filter design (December, p. 206)
•Free software determines telecom system features (December, p. 208)

1999 EDITORIAL INDEX

CONFERENCES

•Next-generation designs unveiled at Wireless Symposium (March, p. 31)
•Products and technologies shine at Wireless Show (March, p. 115)
•1999 International Microwave Symposium (May, p. 130)
•New Orleans to host fall Wireless Symposium (August, p. 130)
•Device speeds increase at 45th annual IEDM (November, p. 43)
•Emerging applications boost Eighth Wireless Symposium (December, p. 122)

CROSSTALK

•Dave McCurdy, CEO of the Electronic Industries Alliance (January, p. 42)
•John Cline, President of Oak Frequency Control (April, p. 40)
•John Ocampo, Founder and President of Stanford Microdevices (May, p. 40)
•Ed Garcia, President of Noise Com, Inc. (July, p. 40)

DEFENSE ELECTRONICS

•Electronics are a secret weapon in the military budget (June, p. 27)
•Firm invests in its future (June, p. 138)
•Portable ELINT system captures data from 0.5 to 18 GHz (September, p. 150)

DEVICES & ICs

•Cellular ICs move toward 3G wireless—gingerly (February, p. 31)
•Antenna/IC combination improves short-range communications (February, p. 53)
•Chip integrates versatile RF/digital interface (February, p. 125)
•Amplifiers take mystery out of linear performance (February, p. 138)
•SiGe yields first commercial products (February, p. 140)
•Chip set supports two-way messaging (February, p. 146)
•Create a low-cost data transceiver (March, p. 85)
•ADC captures 1 GSamples/s (March Cover, p. 128)
•DSP enhances performance of wireless base stations (March, p. 138)
•Nodal voltages offer key to filter design (April, p. 72)
•Build GaAs modules in high volumes (April, p. 99)
•Radio transceiver fits on single IC (April, p. 138)
•Broadband MMIC downconverter does not have any active elements (May, p. 98)
•Mentor program leads to design and fabrication of Ka-band module (May, p. 110)
•Technology determines IC cost and performance (May, p. 117)
•PTFE dielectric raises trimmer reliability (May, p. 208)
•Device supplier adds LDMOS to lineup (May, p. 222)
•GaAs FET sets standard with 60 W at C-band (May, p. 226)
•Design automation aids foundry growth (June, p. 80)
•GaAs ICs optimize optical data systems (June, p. 125)
•Optical devices fire 10-Gb/s systems (June, p. 134)
•FSK modulator boasts high DC accuracy (August, p. 69)
•Fractional-N synthesizers meet HSCSD and GPRS demands (August, p. 105)
•CDMA/AMPS chips enable dual-band transceivers (August, p. 147)
•Create a transceiver IC for triple-band GSM applications (September, p. 80)
•Revolutionary RF IC performs RMS-to-DC conversion (September Cover, p. 140)
•SiGe technology makes practical advances (October, p. 121)
•SiC MESFET delivers 10-W power at 2 GHz (October, p. 138)
•Switch solution integrates GaAs and Si ASIC (October, p. 140)
•Compact RF module fits CDMA base stations (November, p. 132)
•Chip antenna reduces cell-phone dimensions (November, p. 182)
•Bluetooth section (December, p. 145)
•High-power MOSFET targets VHF applications (December, p. 228)
•Front-end RF IC reaches 6 GHz (December, p. 238)
•Power module line expands to suit DCS and PCS (December, p. 239)
•Radio chip set works with direct conversion (December, p. 244)
•Dual-band RF synthesizer enables fast data communications (December, p. 245)

MATERIALS

•Thick-film technology offers high packaging density (February, p. 77)
•Metal-injection molding cuts packaging costs (February, p. 118)
•Novel package improves MOSFET reliability (April Cover, p. 131)
•Packaging technique shrinks RF components (April, p. 149)
•Plastic RF power packages overtake ceramics (June, p. 89)
•Material advances fuel wireless growth (July, p. 95)
•Engineering kit tames pesky RF problems (September, p. 156)

•Comparing round and rectangular crystals (November, p. 85)

SYSTEMS & SUBSYSTEMS

•Time-stretch preprocessing overcomes ADC limitations (March, p. 57)
•Time-stretch methods capture fast waveforms (April, p. 62)
•Analyze noise from co-located transmitters (May, p. 122)
•Novel multiple-beam antenna array serves mobile BTS (August, p. 59)
•Supplying power for wireless data-communications systems (September, p. 90)
•Predict effects of ice needles on satcom performance (October, p. 104)
•Feedforward amplifiers power base stations to 400 W (October, p. 145)
•Switched filter channelizer enhances receiver performance (November, p. 173)
•Optical transceivers transport multiple carriers (November, p. 175)
•Calculate power in Gaussian-modulated wireless systems (December, 101)
•Apply optical WDM to wireless systems (December, p. 177)
•Multiport system speeds production (December, p. 192)
•System automates power-amp testing (December Cover, p. 213)

TEST & MEASUREMENT

•Software invades hardware in new test equipment (January, p. 34)
•Instrument advances enable high-speed power measurements (January, p. 59)
•Probing concerns influence high-speed measurements (January, p. 69)
•Fully characterize balanced devices (January, p. 90)
•Power meters measure wide-ranging levels (January, p. 101)
•Low-cost VNAs aid wireless tests to 3 GHz (January, p. 129)
•Fast meter gauges next-generation power (January, p. 132)
•Portable scopes incorporate DPO technology (January, p. 136)
•Perform multipath testing in high-data-rate systems (February, p. 107)
•Using a spectrum analyzer's video-filter bandwidth (March, p. 94)
•Spectrum analyzer suits noise-parameter testing (March, p. 98)
•Wafer probing fast SONET devices (March, p. 108)
•GSM mobile tester meets need for speed (March, p. 135)
•Low-priced digital scopes offer high-end features (March, p. 144)
•Signal generators support emerging wireless standards (March, p. 150)
•Minimize measurement variances due to noise (April, p. 108)
•Speed is a key parameter for spectrum analyzers (April, p. 114)
•Handheld spectrum analyzer scans 3 GHz (May Cover, p. 201)
•VXI synthesizer speeds testing to 20 GHz (May, p. 210)
•Synthesizer refinements focus on production test (May, p. 213)
•Switches route signals for wireless production testing (May, p. 216)
•Generator delivers 16 simultaneous signals (May, p. 225)
•Enhanced electronic calibration reduces product testing costs (June, p. 58)
•Designing production shielded RF fixtures (June, p. 69)
•Network analyzers offer test flexibility (July, p. 118)
•Test system monitors spacecraft communications (July, p. 122)
•Perform production testing on millimeter-wave MMICs (August, p. 98)
•Signal generators offer enhanced spectral purity (August, p. 157)
•Spectrum analyzers geared to production testing (August, p. 159)
•Test system tackles CATV components (September, p. 117)
•Instrument makers adapt to evolving applications (September, p. 121)
•Wide-range sensor gauges power of complex signals (September, p. 128)
•Measure digital satellite signals accurately (October, p. 68)
•Meeting the test needs of millimeter-wave MMICs (October, p. 86)
•Calculate the uncertainty of NF measurements (October, p. 93)
•Measure residual noise in quartz crystals (November, p. 95)
•Analysis power added to universal power meters (November, p. 170)
•Gauging the effects of cell-phone radiation on the brain (December, p. 90)
•Spectrum analyzers facilitate high-volume production testing (December, p. 234)
•Noise modules track receiver fidelity (December, p. 240)